

Amendments to the Specification:

Please change the title to read --WAFER HAVING ALIGNMENT MARKS EXTENDING FROM A FIRST TO A SECOND SURFACE OF THE WAFER--

Please replace the paragraph extending from page 17, line 10 to line 14, with the following rewritten paragraph:

This application is related to Glenn et al., co-filed and commonly assigned U.S. Patent Application Serial No. ~~{ATTORNEY DOCKET NUMBER G0049M}~~ 09/803,083 entitled "BACK-SIDE WAFER SINGULATION METHOD", which is herein incorporated by reference in its entirety.